



Date : 20th/Jan/2020

Doc. No.: 22119005

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QC Manager

Power Device Quality Control Dept.

ROHM Co.,LTD

### Product/Process Change Notification

Dear Customer,

This is an announcement of change(s) to the process being used for the products currently supplied.

We request your acknowledgement to receive this notification within the given period.

Please reply by: 3/31/2020

Title of change	SiC module wafer size change to 6inch (Vol.2 of 221800F)		
Affected product(s)	Product name	Customer part number	
	BSM300D12P2E001, BSM400D12P2G003		
Detailed description of change	Now	After	
	Wafer size : 4inch	Wafer size : 6inch	
Reason for change	Improve production capacity by wafer size enlargement and increase production.		
Anticipated impact on quality	(form, fit, function, reliability)		
	No specification change on Dimension, electrical characteristic and reliability.		
Identification of change	Able to identify by the lot No.		
Planned date of change	1st/Apr/2020	Sample availale schedule	Please contact Sales
Attachments (data, report)	YES	4ME_2219005.pdf	
Comments	If no reply is received before the requested date of reply, we will consider this PCN accepted by the customer.		

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